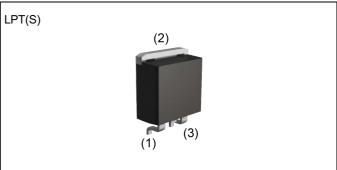


V _{DSS}	650V
R _{DS(on)} (Max.)	1.050Ω
I _D	±4.0A
P _D	58W

Outline



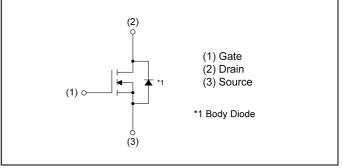
Inner circuit



Application

Switching

- 2) Ultra fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating ; RoHS compliant



Packaging specifications

Packing	Embossed Tape
Packing code	TL
Marking	R6504KNJ
Basic ordering unit (pcs)	1000

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V _{DSS}	650	V
Continuous drain current $(T_c = 25)$	5°C)	۱ _D *1	±4.0	А
Pulsed drain current		I _{DP} *2	±12	А
Cata Cauraa valtaara	Static	N/	±20	V
Gate - Source voltage	AC (f>1Hz)	V_{GSS}	±30	V
Avalanche current, single pulse		I _{AS}	0.8	А
Avalanche energy, single pulse		E _{AS} *3	34.8	mJ
Power dissipation $(T_c = 25^{\circ}C)$	P _D	58	W	
Junction temperature	Tj	150	°C	
Operating junction and storage te	T _{stg}	-55 to +150	°C	

•Thermal resistance

Deremeter	Cumph of	Values			Lincit	
Parameter	Symbol	Min.	Тур.	Max.	Unit	
Thermal resistance, junction - case	R_{thJC}^{*4}	-	-	2.2	°C/W	
Thermal resistance, junction - ambient	R_{thJA}^{*5}	-	-	80	°C/W	
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C	

•Electrical characteristics (T_a = 25°C)

Deremeter	Sumbol	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA	650	-	-	V	
		V _{DS} = 650V, V _{GS} = 0V					
Zero gate voltage drain current	I _{DSS}	$T_j = 25^{\circ}C$	-	-	100	μA	
		T _j = 125°C	-	-	1000		
Gate - Source leakage current	I _{GSS}	V_{GS} = ±20V, V_{DS} = 0V	-	-	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	V_{DS} = V_{GS} , I_D = 130 μ A	3	-	5	V	
		V _{GS} = 10V, I _D = 1.5A					
Static drain - source on - state resistance	R _{DS(on)} *6	$T_j = 25^{\circ}C$	-	0.955	1.050	Ω	
		T _j = 125°C	-	-	-		
Gate resistance	R _G	f = 1MHz, open drain	-	3.3	-	Ω	



•Electrical characteristics (T_a = 25°C)

Deremeter	Sympol	Conditions	Values			Linit
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	270	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	270	-	pF
Reverse transfer capacitance C _{rss}		f = 1MHz	-	15	-	
Turn - on delay time	t _{d(on)} *6	$V_{DD} \simeq 300 V, V_{GS}$ = 10V	-	16	-	
Rise time	t _r *6	I _D = 2A	-	17	-	20
Turn - off delay time t _{d(c}		$R_L \simeq 150\Omega$	-	30	-	ns
Fall time	t _f *6	R _G = 10Ω	-	35	-	

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Deremeter	C: make al	Conditions	Values			Unit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Orm	
Total gate charge	Q_g^{*6}	$V_{DD} \simeq 300V$	-	10	-		
Gate - Source charge	Q _{gs} *6	I _D = 4A	-	2.5	-	nC	
Gate - Drain charge	Q_{gd}^{*6}	V _{GS} = 10V	-	4.8	-		
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 300$ V, I _D = 4A	-	6.5	-	V	

*1 Limited only by maximum channel temperature allowed.

- *2 Pw \leq 10µs, Duty cycle \leq 1%
- *3 L \doteqdot 100mH, V_{DD}=50V, R_G=25 Ω , STARTING T_i=25°C
- *4 T_C=25°C
- *5 Mounted on an epoxy PCB FR4 (25mm x 27mm x 0.8mm)
- *6 Pulsed



•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Source current	ا _S *1	-		-	4.0	А	
Pulsed source current	I_{SP}^{*2}	T _C = 25°C	-	-	12	А	
Source-Drain voltage	V_{SD}^{*6}	V _{GS} = 0V, I _S = 4A	-	-	1.5	V	
Reverse recovery time	t _{rr} *6		-	290	-	ns	
Reverse recovery charge	Q_{rr}^{*6} $I_S = 4A$ di/dt = 100A/µs	•	-	1.9	-	μC	
Peak reverse recovery current	۲ _{rr} *6		-	13	-	А	





• Electrical characteristic curves

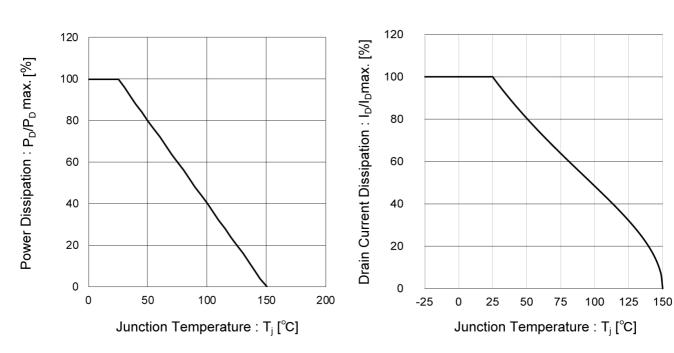


Fig.1 Power Dissipation Derating Curve

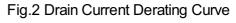


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

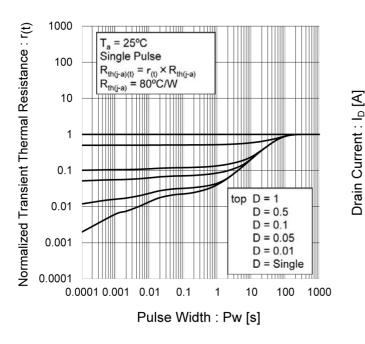
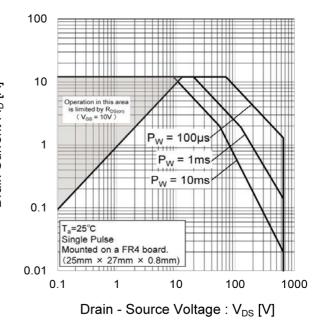


Fig.4 Maximum Safe Operating Area





• Electrical characteristic curves

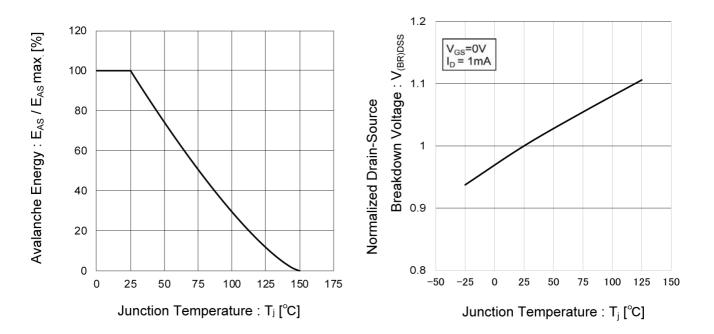
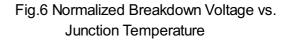


Fig.5 Avalanche Energy Derating Curve





Drain Current : I_D [A]

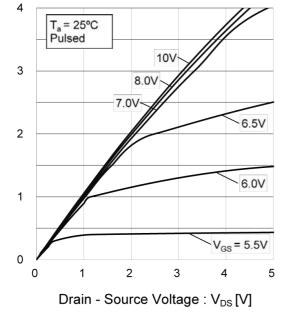
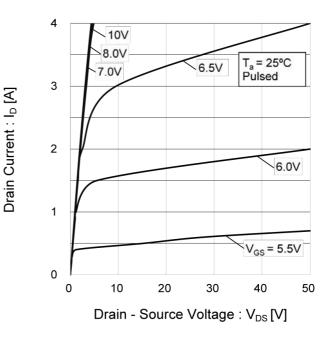


Fig.8 Typical Output Characteristics(II)





Electrical characteristic curves

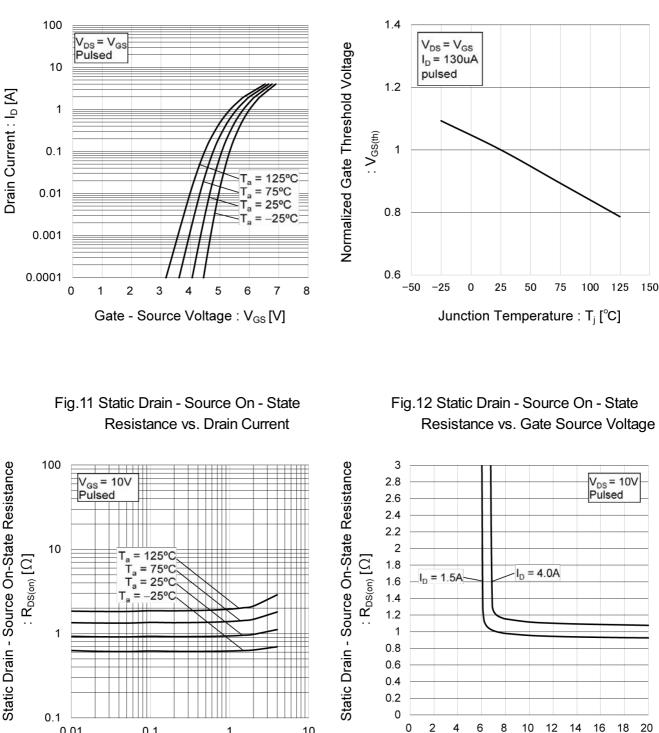
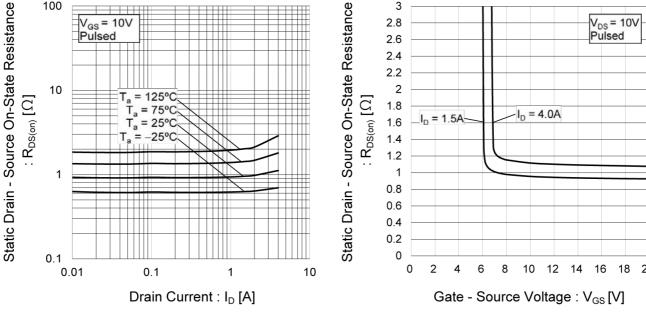


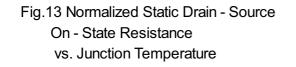
Fig.9 Typical Transfer Characteristics

Fig.10 Normalized Gate Threshold Voltage vs. Junction Temperature





•Electrical characteristic curves



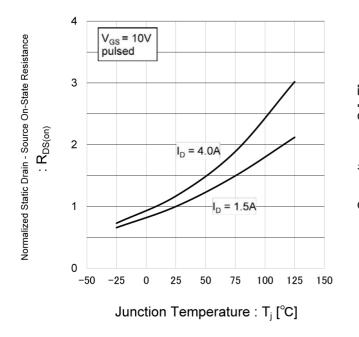


Fig.14 Typical Capacitance vs. Drain - Source Voltage

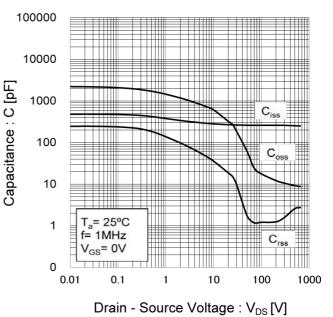


Fig.15 Switching Characteristics

Fig.16 Typical Gate Charge

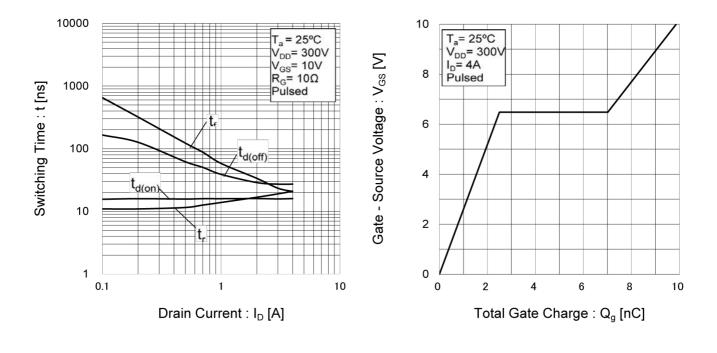




Fig.18 Reverse Recovery Time vs.

Inverse Diode Forward Current

• Electrical characteristic curves

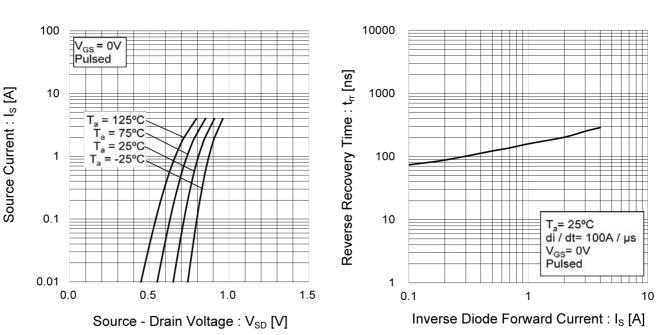


Fig.17 Source Current vs. Source - Drain Voltage





Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

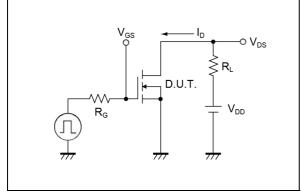


Fig.2-1 Gate Charge Measurement Circuit

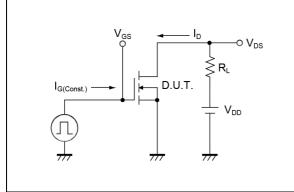


Fig.3-1 Avalanche Measurement Circuit

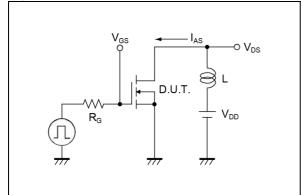


Fig.4-1 trr Measurement Circuit

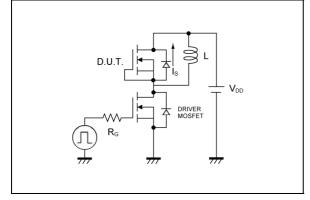


Fig.1-2 Switching Waveforms

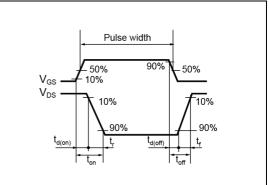


Fig.2-2 Gate Charge Waveform

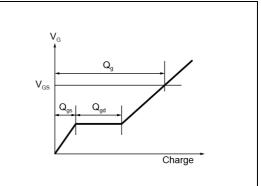


Fig.3-2 Avalanche Waveform

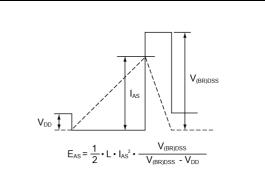
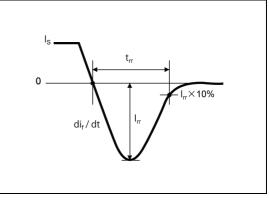
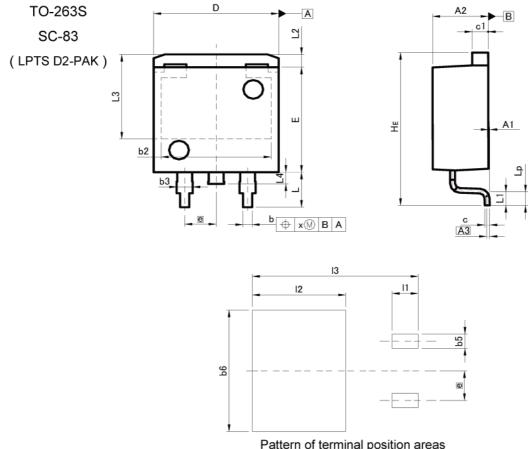


Fig.4-2 trr Waveform





Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES	
DIM -	MIN	MAX	MIN	MAX	
A1	0.00	0.30	0.000	0.012	
A2	4.30	4.70	0.169	0.185	
A3	0.	25	0.0	10	
b	0.68	0.98	0.027	0.039	
b2	8.	90	0.3	50	
b3	1.14	1.44	0.045	0.057	
C	0.30	0.60	0.012	0.024	
c1	1.10	1.50	0.043	0.059	
D	9.80	10.40	0.386	0.409	
E	8.80	9.20	0.346	0.362	
e	2.	54	0.1	00	
HE	12.80	13.40	0.504	0.528	
L	2.70	3.30	0.106	0.130	
L1	1.	20	0.047		
L2	1.	10	0.0	43	
L3	7.	25	0.2	85	
L4	1.	00	0.0	39	
Lp	0.90	1.50	0.035	0.059	
x	7 2	0.25	-	0.010	
	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
b5	.	1.23	-	0.049	
b6		10.40		0.409	
11	<u> </u>	2.10	1 <u>12</u>	0.083	
12		7.55	1. 1977 - 1	0.297	
13	-	13.40	-	0.528	

Dimension in mm/inches



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	JAPAN	USA	EU	CHINA
I	CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
	CLASSⅣ	CLASSII	CLASSII	CLASSI

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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When disposing Products please dispose them properly using an authorized industry waste company.

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